



# BRIGHTTEK

BRIGHTTEK (EUROPE) LIMITED

*Brighten up The World With LED!*



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

## PRODUCT DATASHEET

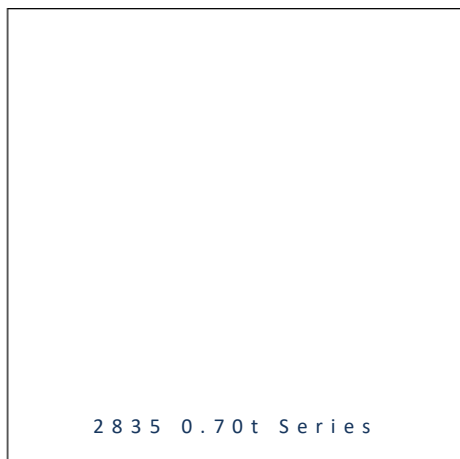


- ▶ PLCC2 Top View SMD
- ▶ 2835 0.70t
- ▶ PC Amber 590nm

# N0A69S55PC



Release Date: 04 March 2025 Version: A1.1



2835 0.70t Series

## 2835 0.70t Series

**RoHS**  
Compliant



### FEATURES:

- **Package:** PLCC2 Single Colour Top View SMD
- **Forward Current:** 60mA
- **Forward Voltage (typ.):** 3.2V
- **Luminous Flux (typ.):** 24lm@60mA
- **Colour:** PC Amber
- **Dominant Wavelength (typ.):** 591nm
- **Viewing Angle:** 120°
- **Materials:**
  - Resin: Silicone (Yellow Diffused)
  - Finishing: Ag plated
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+85°C
- **ESD (HBM):** 1000V
- **Grouping Parameters:**
  - Forward Voltage
  - Luminous Flux
  - CIE Chromaticity
- **Soldering Methods:** Reflow
- **MSL Level:** acc. to JEDEC Level 5a
- **Packing:** 8mm tape with max.4000/reel, ø178mm (7")

### APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard
- Decoration Lighting

## CHARACTERISTICS:

### Absolute Maximum Characteristics ( $T_a=25^{\circ}\text{C}$ )

Parameter	Symbol	Ratings	Unit
Forward Current	$I_F$	60	mA
Peak Forward Current Duty 1/10; width 0.1ms	$I_{FP}$	150	mA
Power Dissipation	$P_D$	0.2	W
Reverse Voltage	$V_R$	5	V
Reverse Current @8V	$I_R$	10	$\mu\text{A}$
Electrostatic Discharge (HBM)	ESD	1000	V
Operating Temperature	$T_{OPR}$	$-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$	$^{\circ}\text{C}$
Storage Temperature	$T_{STG}$	$-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$	$^{\circ}\text{C}$
Soldering Temperature	$T_{SOL}$	260 for 5S	$^{\circ}\text{C}$

### Electrical & Optical Characteristics ( $T_a=25^{\circ}\text{C}$ )

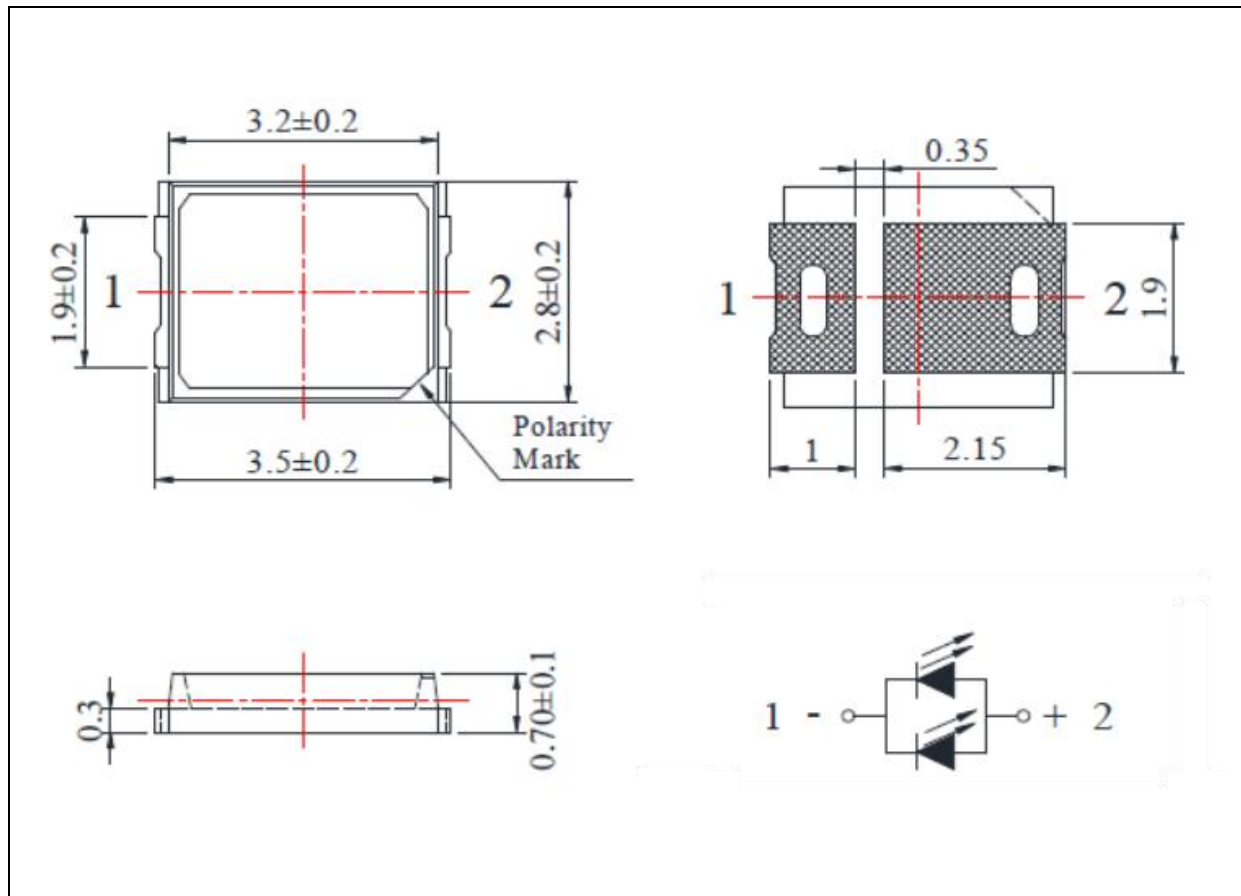
Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	$V_F$	2.8	3.2	3.6	V	$I_F=60\text{mA}$
Luminous Flux	$\Phi_V$	20	24	---	lm	$I_F=60\text{mA}$
Chromaticity Coordinates	X	---	0.5700	---	---	$I_F=60\text{mA}$
	Y	---	0.4200	---		
Colour Temperature	CCT	1600	1750	2000	K	$I_F=60\text{mA}$
Dominant Wavelength	$\lambda_D$	588	591	595	nm	$I_F=60\text{mA}$
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	$I_F=60\text{mA}$

1. Luminous intensity ( $I_v$ )  $\pm 10\%$ , Forward Voltage ( $V_F$ )  $\pm 0.1\text{V}$ .



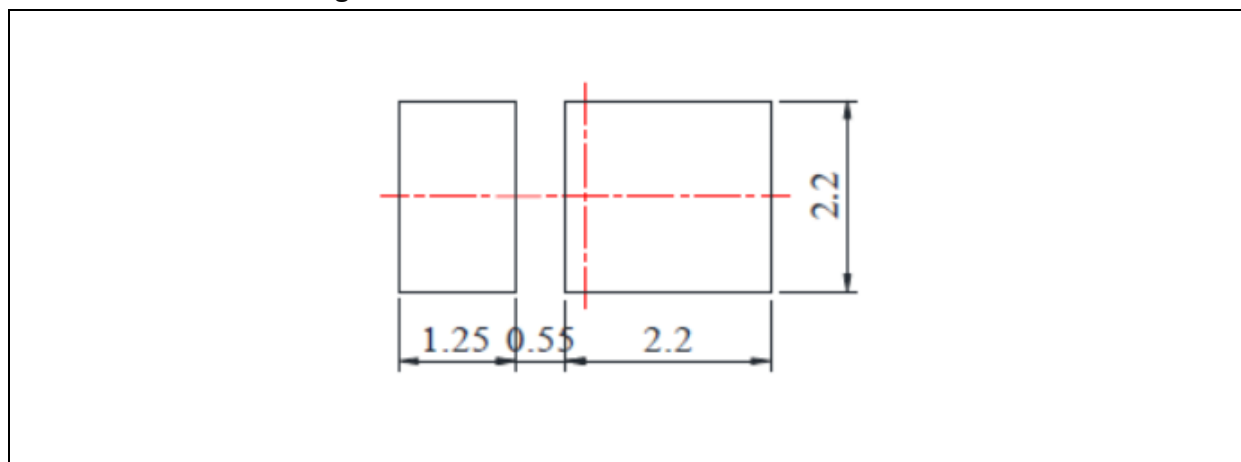
## OUTLINE DIMENSION:

### Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.2$ mm, unless otherwise noted.

### Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1$ mm with angle tolerance  $\pm 0.5^\circ$ .

## BINNING GROUPS:

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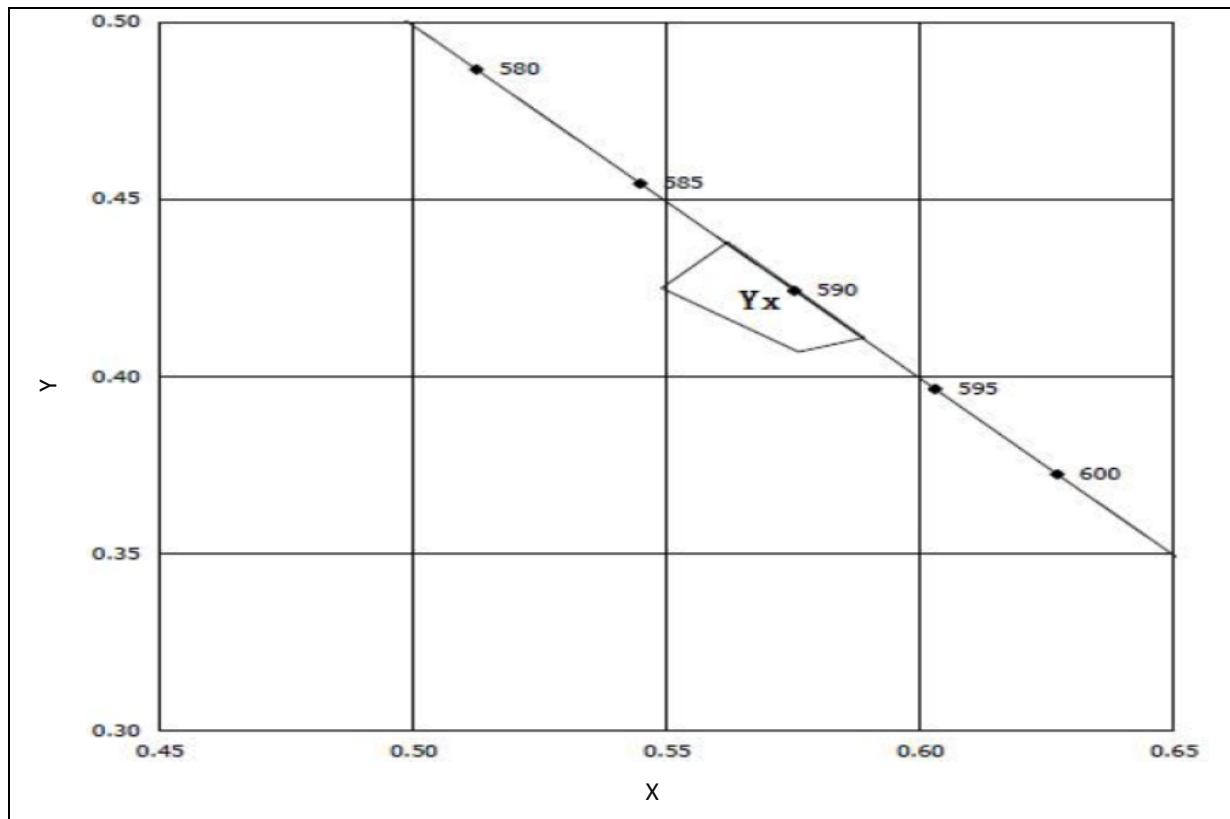
Forward Voltage Classifications ( $I_F = 60\text{mA}$ ):

Code	Min.	Max.	Unit
VF2830	2.8	3.0	V
VF3032	3.0	3.2	
VF3234	3.2	3.4	

Luminous Flux Classifications ( $I_F = 60\text{mA}$ ):

Code	Min.	Max.	Unit
L2022	20	22	lm
L2224	22	24	
L2426	24	26	

## CIE CHROMATICITY DIAGRAM:

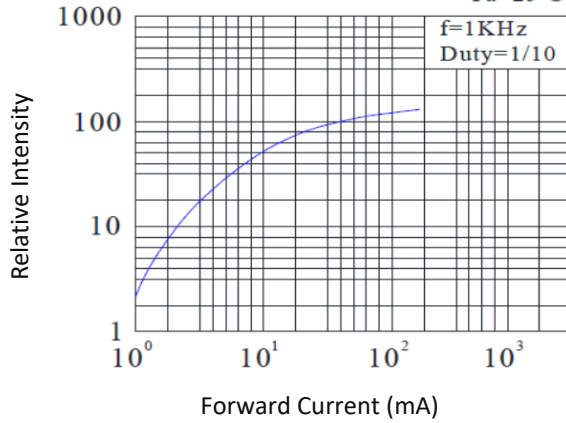


Chromaticity Coordinates Classifications ( $I_F = 60\text{mA}$ ):

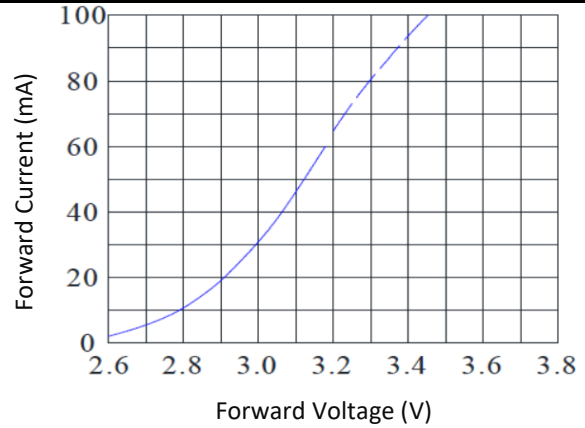
	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
$Y_x$	0.5760	0.4070	0.5490	0.4250	0.5620	0.4380	0.5890	0.4110

## ELECTRO-OPTICAL CHARACTERISTICS:

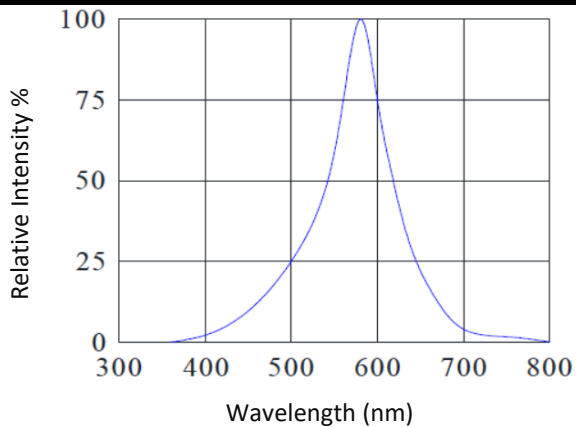
Relative Intensity v.s. Forward Current



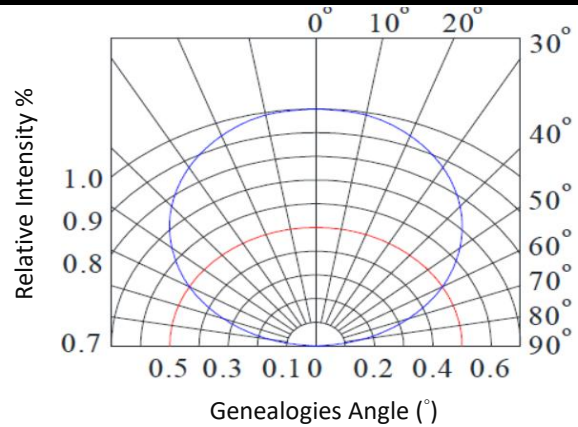
Forward Current v.s. Forward Voltage



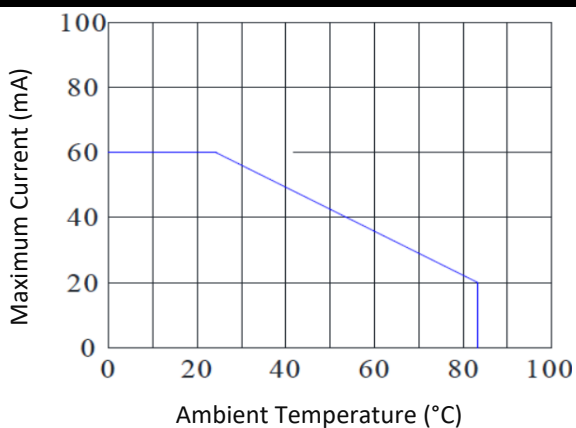
Relative Intensity v.s. Wavelength



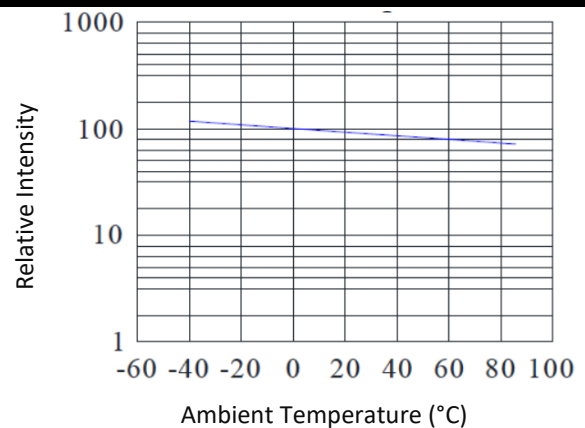
Relative Intensity v.s. Angular Displacement



Temperature Derating Chart



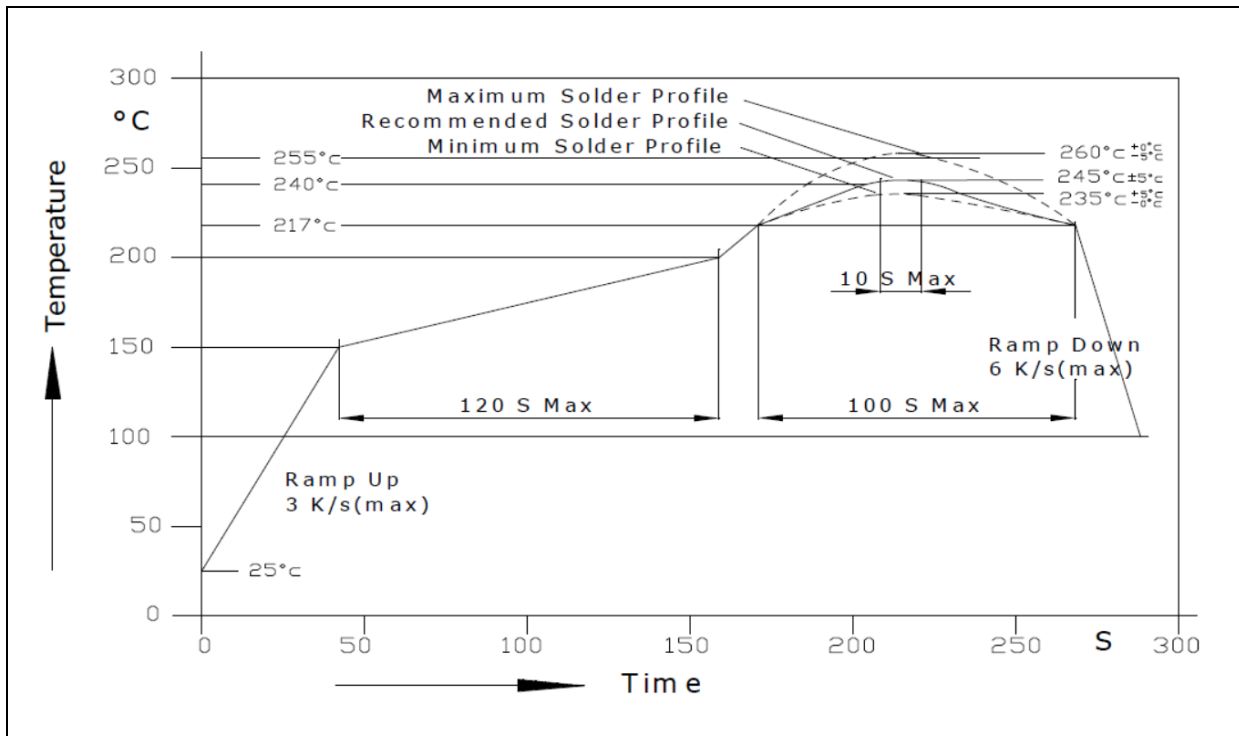
Relative Intensity Flux v.s. Ambient Temperature





## RECOMMENDED SOLDERING PROFILE:

Reflow Solder:



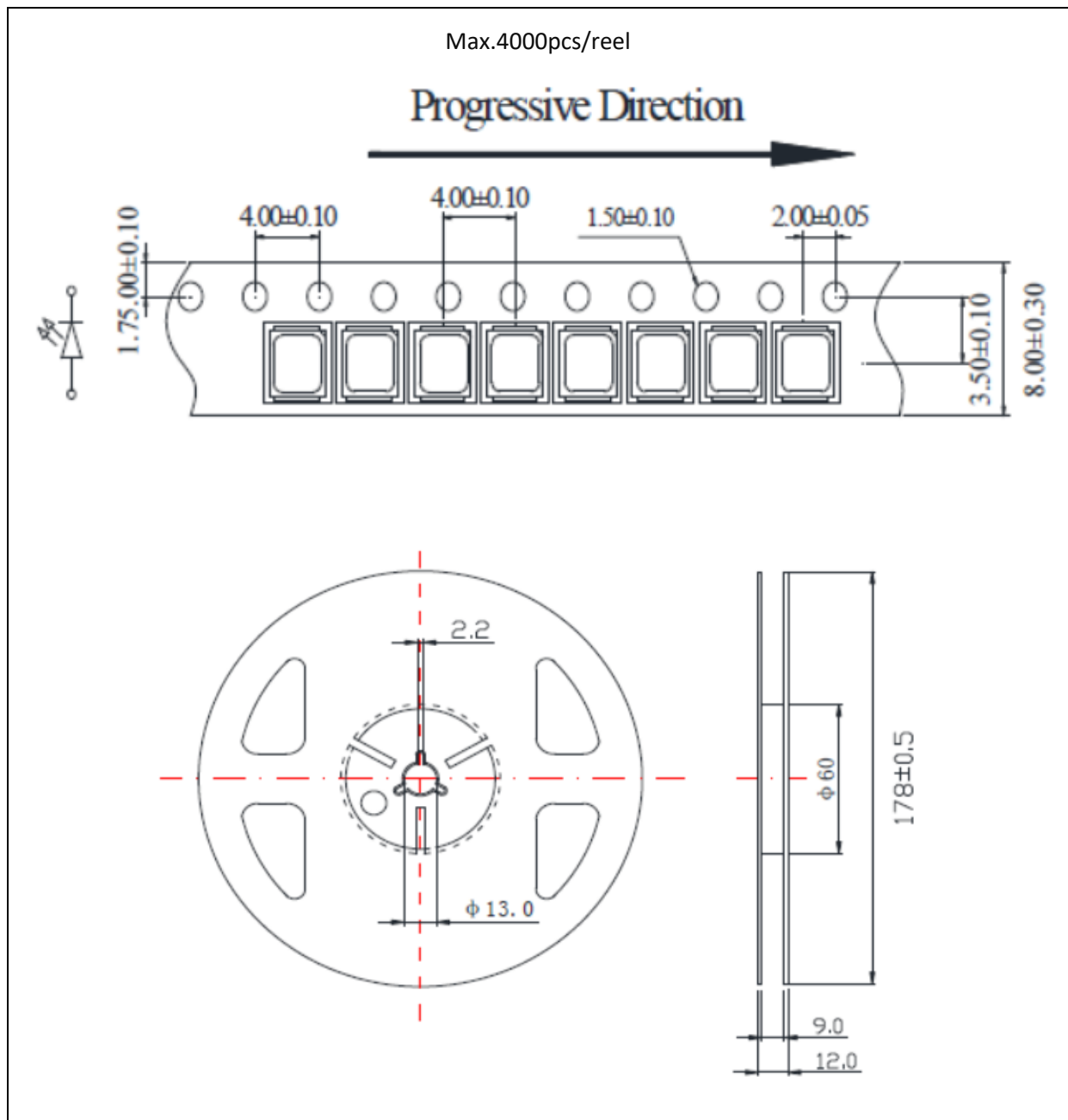
Note:

1. Recommend reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.
2. Maximum reflow soldering: 2 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.



## PACKING SPECIFICATION:

Reel Dimension:





## PRECAUTIONS OF USE:

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### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 24 hours. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

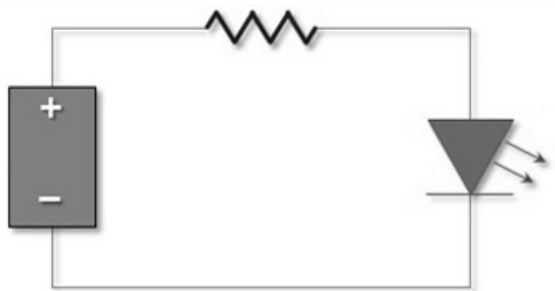
### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### Testing Circuit:



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

**REVISION RECORD:**

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Version	Date	Summary of Revision
A1.0	12/09/2023	Datasheet set-up.
A1.1	04/03/2025	New datasheet format.